

What is claimed is:

1. A compound for removing polymers generated during an etching process, comprising DIW, H₂SO₄, H₂O₂ and HF.
2. The compound of claim 1, wherein DIW occupies by volume about 70.5% to about 80.5%.
3. The compound of claim 2, wherein DIW occupies by volume about 75.5%.
4. The compound of claim 1, wherein H₂SO₄ occupies by volume about 6.5% to about 8.5%.
5. The compound of claim 4, wherein H₂SO₄ occupies by volume about 7.5%.
6. The compound of claim 1, wherein H₂O₂ occupies by volume about 15% to about 19%.
7. The compound of claim 6, wherein H₂O₂ occupies by volume about 17%.
8. The compound of claim 1, wherein HF occupies by volume about 50 PPM to about 150 PPM.

9. A method for removing polymers generated during etching processes, comprising:
- removing the polymers by using an inorganic compound including DIW, H_2SO_4 , H_2O_2 and HF;
 - forming a protective oxide film on at least one of a metal line, a via hole and a pad open area by using H_2O_2 ; and
 - protecting the at least one the metal line, the via hole and the pad open area by the protective oxide film while removing the polymers by using HF.
10. The method of claim 9, wherein DIW occupies by volume about 70.5% to about 80.5%.
11. The method of claim 10, wherein DIW occupies by volume about 75.5%.
12. The method of claim 9, wherein H_2SO_4 occupies by volume about 6.5% to about 8.5%.
13. The method of claim 12, wherein H_2SO_4 occupies by volume about 7.5%.
14. The method of claim 9, wherein H_2O_2 occupies by volume about 15% to about 19%.
15. The method of claim 14, wherein H_2O_2 occupies by volume about 17%.

16. The method of claim 9, wherein HF occupies by volume about 50 PPM to about 150 PPM.

17. An apparatus for manufacturing a compound for removing polymers generated during etching processes, the apparatus comprising:

a plurality of tanks in which DIW, H₂SO₄, H₂O₂ and HF are stored, respectively;

a main tank for mixing DIW, H₂SO₄, H₂O₂ and HF supplied from the plurality of tanks through supplying tubes connected between the main tank and the plurality of tanks;

flow control devices for controlling flow rates of DIW, H₂SO₄, H₂O₂ and HF, through the supplying tubes; and

a pump for circulating a mixture of DIW, H₂SO₄, H₂O₂ and HF stored in the main tank.